



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Kinsman et al.

Serial No.: 09/538,684

Filed: March 30, 2000

For: VARIED-THICKNESS HEAT SINK
FOR INTEGRATED CIRCUIT (IC)
PACKAGES AND METHOD OF
FABRICATING IC PACKAGES

Confirmation No.: 8722

Examiner: D. Graybill

Group Art Unit: 2827

Attorney Docket No.: 3056.1US (96-803.1)

CERTIFICATE OF MAILING

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RESPONSE TO FINAL OFFICE ACTION

Box AF
Commissioner for Patents
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Sir:

This reply is sent in response to the Final Rejection of the claimed invention in the Office Action of October 22, 2002, whose timely period of response occurs on December 22, 2002, and whose initial period of response is set to expire on January 22, 2003.